

VarioLas

Versatile UV Laser Processing

VarioLas processing systems based on the powerful COMPex excimer laser are flexible tools for high quality UV microprocessing. Superior optics design, rugged mechanics and unmatched pulse-to-pulse stability are the key ingredients to each VarioLas model available at 193 nm, 248 nm, and 308 nm.



FEATURES

- High resolution optics and mechanics ensure reproducible results
- Modular design with tailored options for flexible use
- Square beam and line beam fields for optimum results
- Supports all COMPex laser models to enable efficient processing

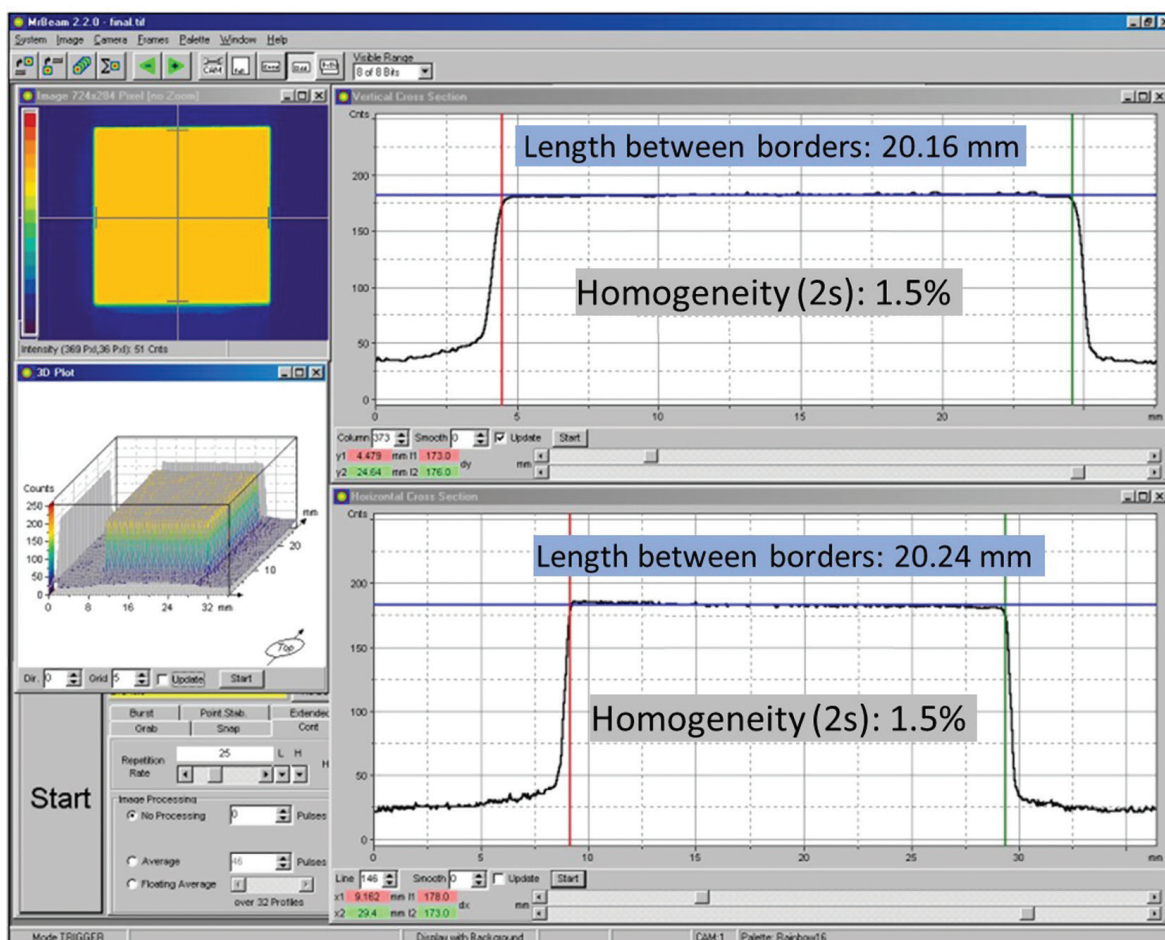
APPLICATIONS

- Laser Lift-Off Separation
- Dopant Ion Activation
- Ablative Patterning
- Excimer Laser Annealing
- Laser-Induced Forward Transfer

Specifications	VarioLas Eco	VarioLas Pro	VarioLas Sweep
Field Geometry	Square		Line
Substrate Field Size (mm ²)	2 x 2		50 x 0.6
Optical Resolution (μm)	30	5	–
Working Distance (mm)	50		150
Maximum Repetition Rate (Hz)	100		100
Maximum Energy Density (J/cm ²)			
at 193 nm	2.5		–
at 248 nm	7.5		1.3
at 308 nm	6.0		1.0
Energy Stability (% , 1 sigma)			
at 193 nm	1.5		–
at 248 nm	0.75		0.75
at 308 nm	0.75		0.75

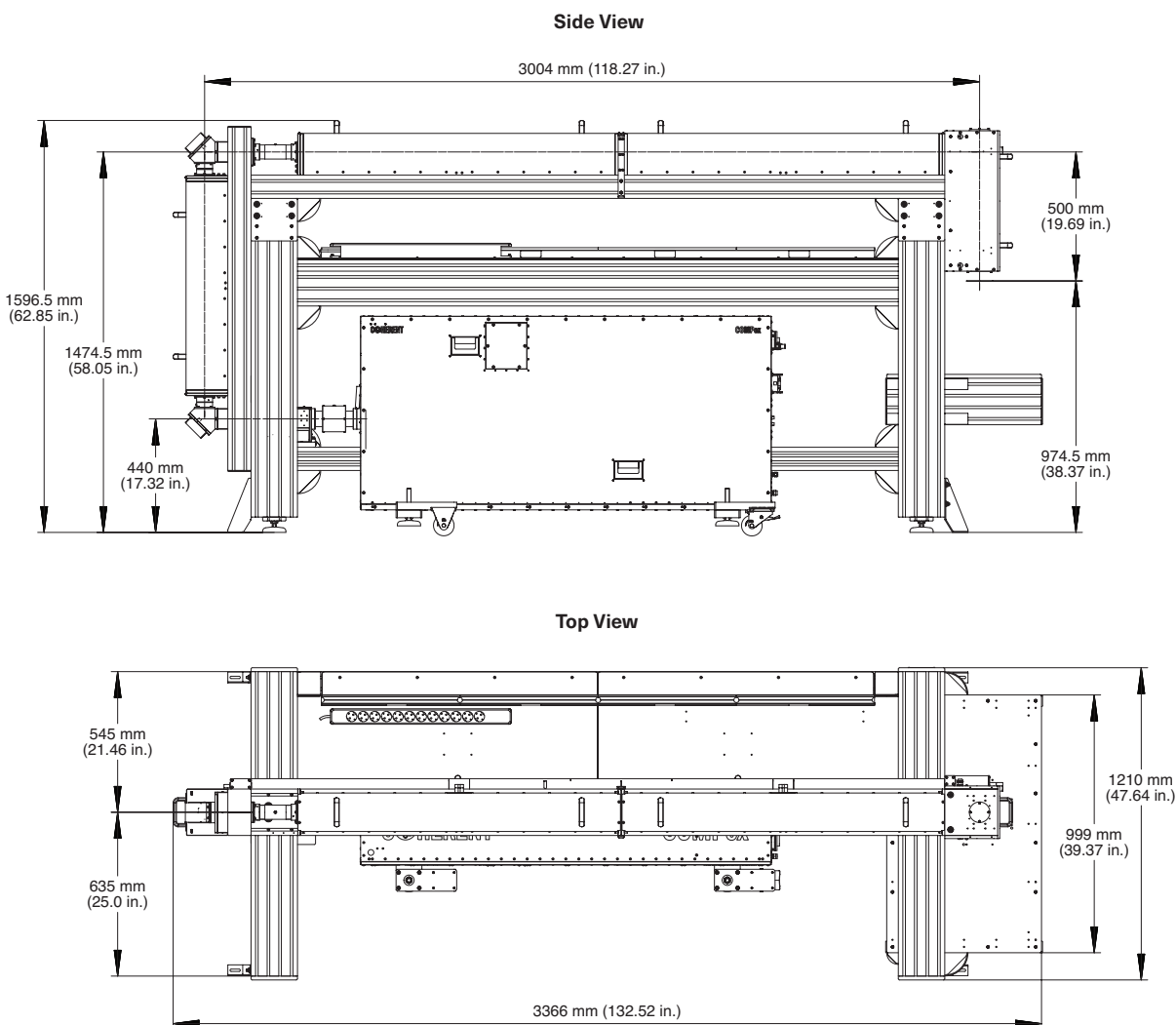
VarioLas Performance

2D-mask plane image of VarioLasPro with cross sections along x- and y-axis.



Mechanical Specifications

VarioLas



CE ISO 9001 Registered

